

E5491-03 (\*)

UNITED STATES (Form BDW-1)  
Patents and Design Patents  
Sole & Joint Inventors  
Convention & Non-convention  
PCT & Non-PCT  
This form cannot be amended, altered  
or changed after it is signed.  
(For use only for inventors who  
understand the English language.)

## Declaration and Power of Attorney United States Patent Application

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

"EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE"

\_\_\_\_\_, the specification of which

- (check one) ☐ is attached hereto.  
☐ was filed on \_\_\_\_\_ as U.S. Application Serial No. \_\_\_\_\_ and (if applicable) was amended on \_\_\_\_\_.  
☒ was filed as PCT International Application No. PCT/JP00/05992 on September 4, 2000 and (if applicable) was amended under PCT Article 19 on \_\_\_\_\_.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, §1.56(a-d).

I hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign and PCT application(s) for patent or inventor's certificate listed in this Declaration and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Foreign/PCT Application No.	Country	Filing Date	Priority Claimed? (yes/no)
11-251600	Japan	September 6, 1999	yes

I hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) and PCT International Application(s) listed in this Declaration and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, §1.56(a-d) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

U.S. Application No.	Filing Date	Status (patented/pending/abandoned?)

I hereby appoint the following attorneys to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith: Joseph A. DeGrandi (17446), Robert G. Weilacher (20531), Richard G. Young (20628), Michael A. Makuch (32263), Dennis C. Rodgers (32936), William F. Rauchholz (34791), G. Byron Stover (34737), Thomas L. Evans (35805), Maurice U. Cahn (30454), and William J. Bundren (31712).

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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or first inventor: Hironori OSUGA Citizenship: Japan

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Signature: Hironori Osuga Date: March 23, 2001

Full name of second joint inventor, if any:

Citizenship:

Residence (city, state, country):

Post office address:

Signature: \_\_\_\_\_ Date: \_\_\_\_\_